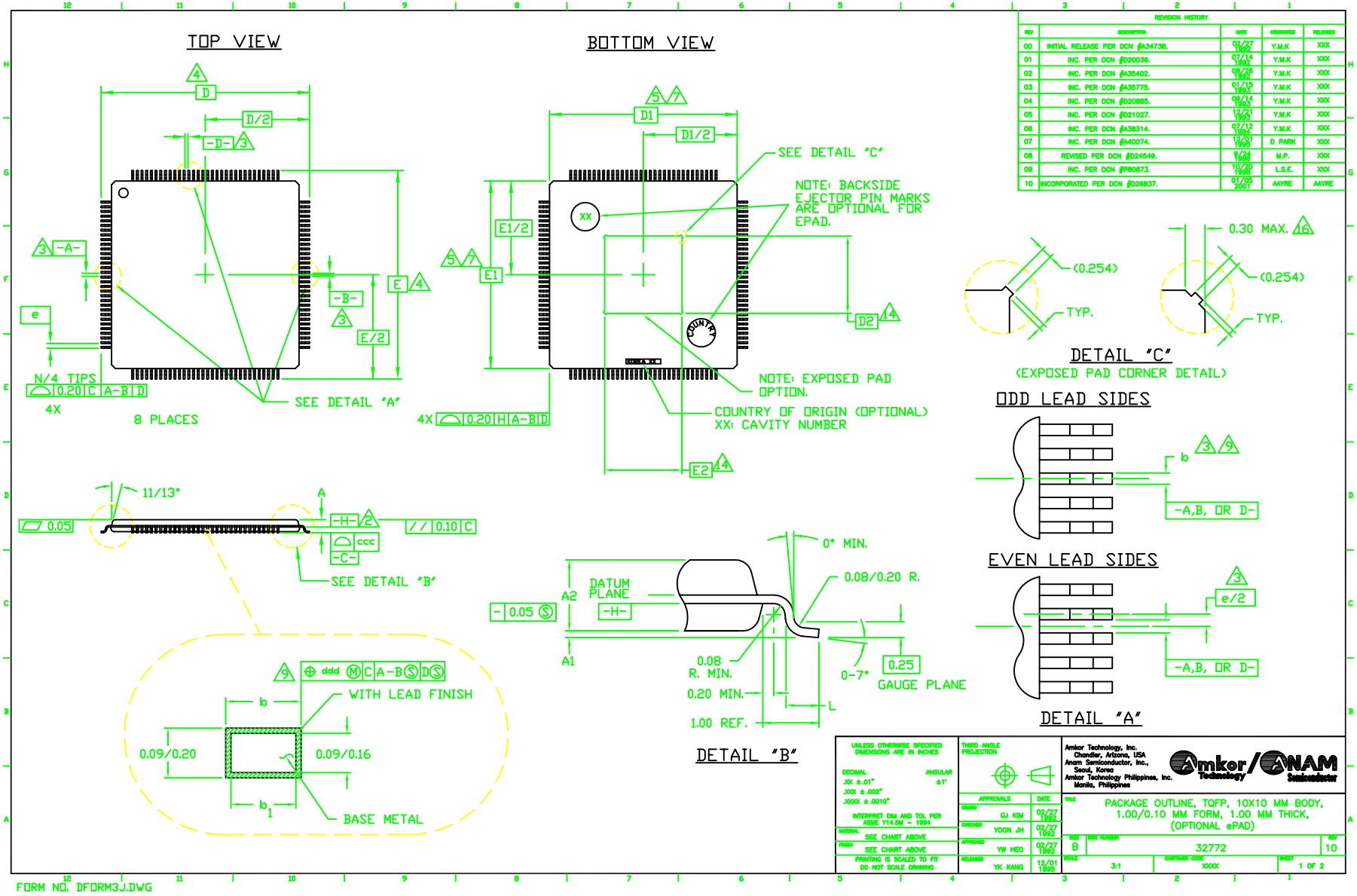

REVISION HISTORY				
REV	DESCRIPTION	DATE	ORIGINATED	RELEASED
00	INITIAL RELEASE PER DCN #A34738.	02/27 1992	Y.M.K	XXX
01	INC. PER DCN #020036.	07/14 1992	Y.M.K	XXX
02	INC. PER DCN #A35402.	08/26 1992	Y.M.K	XXX
03	INC. PER DCN #A35775.	01/19 1993	Y.M.K	XXX
04	INC. PER DCN #020885.	08/14 1993	Y.M.K	XXX
05	INC. PER DCN #021027.	12/31 1993	Y.M.K	XXX
06	INC. PER DCN #A38314.	07/12 1994	Y.M.K	XXX
07	INC. PER DCN #A40074.	12/31 1995	D PARK	XXX
08	REVISED PER DCN #024549.	9/24 1998	M.P.	XXX
09	INC. PER DCN #F80673.	10/20 1998	L.S.E.	XXX
10	INCORPORATED PER DCN #026837.	01/05 2001	AAYRE	AAYRE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
DECIMAL: .XX ±.01" .XXX ±.002" .XXXX ±.0010"
ANGULAR: ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 1994
MATERIAL: SEE CHART ABOVE
FINISH: SEE CHART ABOVE
PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS		DATE
DRAWN	GJ KIM	02/27 1992
CHECKED	YOON JH	02/27 1992
APPROVED	YW HEO	02/27 1992
RELEASED	YK KANG	12/01 1995

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

TITLE: PACKAGE OUTLINE, TQFP, 10X10 MM BODY, 1.00/0.10 MM FORM, 1.00 MM THICK, (OPTIONAL ePAD)

SIZE	DWG NUMBER	REV
B	32772	10
SCALE: 3:1	CUSTOMER CODE: XXXX	SHEET: 1 OF 2

FORM NO. DFORM3J.DWG